

LOCTITE ABLESTIK ATB 120US1

July 2019

PRODUCT DESCRIPTION

LOCTITE ABLESTIK ATB 120US1 provides the following product characteristics:

Technology	Epoxy Film
Appearance	Transparent
Cure	Skip-Cure Process
Product Benefits	Long thermal budget
	 Meets thin wafer requirements
	Co-curable during molding process
	 Consistent dicing and die pickup for
	large die applications
Application	Encapsulation or Semi-Films
Filler Type	Silica
Typical Package	Die to die stack and Die to substrate
Application	
Carrier Type	Polyolefin
Adhesive Thickness	20μm
Carrier Film Thickness	90μm
Wafer Size in	8 and 12 in

LOCTITE ABLESTIK ATB 120US1 adhesive film with UV dicing tape is formulated for use in wafer lamination processes or as a preform decal.

It is designed for use in both mother/daughter die in stack packages.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Work Life @ 25°C, days	90
Shelf Life @ 5°C (from date of manufacture), days	365

TYPICAL PROCESS DATA

Wafer Backside Lamination

Temperature, °C	65
Pressure, psi	30
Taping Duration, ft/ minute	1

Chip Attach

Temperature, °C	100 to 130
Pressure, kg-f	0.5 to 1.0
Attach Duration, second	0.5 to 1.0

TYPICAL UV IRRADIATION

U	V	Li	g	ht

UV Dosage, mJ/cm²	200
UV Wavelength, nm (UVA)	365

TYPICAL CURING PERFORMANCE

SkipCure Process

Cured at post mold cure

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties

,		
Coefficient of Thermal Expansion, TMA:		
Below Tg, ppm/°C		81
Glass Transition Temperature (Tg) by DMTA,	°C	41
Tensile Modulus, DMTA:		
@ -65 °C		3,505 (508,357)
@ 25 °C	N/mm²	1,277 (185,213)
@ 150 °C	N/mm² (psi)	2.4
@ 200 °C	N/mm² (psi)	2.0
@ 250 °C	N/mm² (psi)	`1.9 [′]
Extractable Ionic Content, :	. ,	, ,
Chloride (CI-)		7
Sodium (Na+)		6
Potassium (K+)		2
Weight Loss @ 250°C, %		0.6
Moisture Absorption @ Saturation, after 85 exposure, wt %	°C/85%	RH 1.8

TYPICAL PERFORMANCE OF CURED MATERIAL

Thermal Budget @ 175°C, hours >4
Die Shear Strength vs Temperature, kg-f:
2.5 X 2.5 mm Si die. kg-f.

Z.O X Z.O IIIIII OI ale, kg i,	
Die on Substrate:	@260°C
BT Substrate	1.0

GENERAL INFORMATION

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.



DIRECTIONS FOR USE

- Ensure all surfaces to be bonded are free from surface contamination.
- Adhesive must be completely used within the product's recommended work life.
- Remove the tape reel from the moisture-resistant package and load into the tape application machine.
- Store unused adhesive film in the original sealed moistureresistant package until needed.

STORAGE:

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: 5°C. Storage below 5°C or greater than 5°C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

(°C x 1.8) + 32 = °F kV/mm x 25.4 = V/mil mm / 25.4 = inches N x 0.225 = lb/F N/mm x 5.71 = lb/in psi x 145 = N/mm² MPa = N/mm² N·m x 8.851 = lb·ft N·m x 0.738 = lb·ft N·m x 0.142 = oz·in mPa·s = cP

Disclaimer

Note:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

In case products are delivered by Henkel Belgium NV, Henkel Electronic Materials NV, Henkel Nederland BV, Henkel Technologies France SAS and Henkel France SA please additionally note the following:

In case Henkel would be nevertheless held liable, on whatever legal ground, Henkel's liability will in no event exceed the amount of the concerned delivery.

In case products are delivered by Henkel Colombiana, S.A.S. the following disclaimer is applicable:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

In case products are delivered by Henkel Corporation, Resin Technology Group, Inc., or Henkel Canada Corporation, the following disclaimer is applicable:

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Corporation's products. Henkel Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits. The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

Trademark usage: [Except as otherwise noted] All trademarks in this document are trademarks and/or registered trademarks of Henkel and its affiliates in the U.S. and elsewhere.

Reference 1

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Loctite:

1471871